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MAY 23 2006

**Reply under 37 CFR 1.116  
Expedited Procedure  
Examining Group1753**

Appl. No.: 10/672,416

Confirmation No.: 8435

Applicant: Tench and White

Examiner: VAN, Luan V.

Filed: 09/26/2003

TC/A.U.: 1753

Title: Improved Copper Bath for  
Electroplating Fine Circuitry on  
Semiconductor Chips

O.A. Date: January 23, 2006

Resp. Date: May 23, 2006

Docket No.: 03RSC004

Customer No.: 56294

Mail Stop AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**REPLY UNDER 37 CFR 1.116**

Sir:

In response to the Office Action of January 23, 2006, please amend the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are not included herein, but a complete listing of the claims begins on page 3 of this paper.

**Amendments to the Drawings** are not included herein.

**Remarks** begin on page 8 of this paper.

**A Petition for Extension of Time** begins on page 10 of this paper.

**A Petition to Claim Priority** begins on page 10 of this paper.